

AMENDMENTS TO THE CLAIMS

1-3. (Canceled)

4. (Previously Presented) An apparatus comprising:

- a base having a first opening of a dimension suitable to pass a light emission therethrough;
- a first side wall coupled to the base and having a second opening of a dimension suitable to pass a light emission therethrough;
- a second side wall coupled to the base and having a reflective component thereon, and the base, the first side wall, and the second side wall define an interior chamber with the reflective component disposed in the interior chamber; and
- a fiber connector extending from an exterior of the first side wall adjacent the second opening,

wherein the second side wall is coupled to the first side wall and the base such that the apparatus comprises a polygon body of trigonal and tetrahedral facets.

5. (Previously Presented) An apparatus comprising:

- a semiconductor laser fixed to a board substrate so that the semiconductor laser emits light in a direction substantially perpendicular to the plane of the board substrate, through an opening in the board substrate;
- a base having a first opening of a dimension suitable to pass a light emission therethrough, fixedly attached to the board substrate so that the first opening aligns with the opening in the board substrate through which the semiconductor laser emits light;
- a first side wall coupled to the base and having a second opening of a dimension suitable to pass a light emission therethrough;
- a second side wall coupled to the base and having a planar reflective component thereon, and the base, the first side wall, and the second side wall define an interior chamber with the planar reflective component disposed in the interior chamber; and
- a fiber connector adapted to accept an LC connector extending from an exterior of the first side wall adjacent the second opening.

6. (Previously Presented) An apparatus comprising:

- a semiconductor laser fixed to a board substrate so that the semiconductor laser emits light in a direction substantially perpendicular to the plane of the board substrate, through an opening in the board substrate;
- a base having a first opening of a dimension suitable to pass a light emission therethrough, fixedly attached to the board substrate so that the first opening aligns with the opening in the board substrate through which the semiconductor laser emits light;
- a first side wall coupled to the base and having a second opening of a dimension suitable to pass a light emission therethrough;
- a second side wall coupled to the base and having a planar reflective component thereon, and the base, the first side wall, and the second side wall define an interior chamber with the planar reflective component disposed in the interior chamber; and
- a fiber connector extending from an exterior of the first side wall adjacent the second opening, wherein the first opening and the second opening are aligned through the reflective component to receive a light emission and the base has a third opening and the first side wall has a fourth opening, and the third and fourth opening are aligned to receive a light transmission.

7. (Canceled)

8. (Previously Presented) A system comprising:

- an optical circuit substrate;
- at least one of a light receiving source and a light emitting source coupled to the optical circuit substrate and aligned so as to receive or emit light through an opening in the optical circuit substrate;
- an optical subassembly coupled to the optical circuit substrates and comprising an input, an output, and a reflective component, the input and reflective component disposed in a path of the at least one of the light receiving source and the light emitting source; and
- a fiber optic connector alignment guide that is adapted to be mated to an LC connector, the fiber optic connector alignment guide coupled to the output of the optical subassembly.

9-10. (Canceled)

11. (Previously Presented) A system comprising:

- an optical circuit substrate;
- at least one of a light receiving source and a light emitting source coupled to the optical circuit substrate and aligned so as to receive or emit light through an opening in the optical circuit substrate;
- an optical subassembly coupled to the optical circuit substrates and comprising an input, an output, and a reflective component, the input and reflective component disposed in a path of the at least one of the light receiving source and the light emitting source; and
- a fiber optic connector alignment guide coupled to the output of the optical subassembly, wherein the optical subassembly comprises a base having the input, a first side wall having the output, and a second side wall comprising the reflective component coupled to the first side wall and the base such that the optical subassembly comprises a polygon body of triangular and tetrahedral facets.

12-21. (Canceled)

22. (Previously Presented) An apparatus comprising:

- a photodetector fixed to a board substrate so that the photodetector receives light from a direction substantially perpendicular to the plane of the board substrate, through an opening in the board substrate;
- a base having a first opening of a dimension suitable to pass a light emission therethrough, fixedly attached to the board substrate so that the first opening aligns with the opening in the board substrate through which the photodetector receives light;
- a first side wall coupled to the base and having a second opening of a dimension suitable to pass a light emission therethrough;
- a second side wall coupled to the base and having a planar reflective component thereon, and the base, the first side wall, and the second side wall define an interior chamber with the planar reflective component disposed in the interior chamber; and

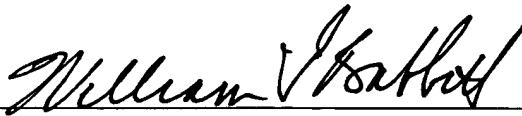
a fiber connector adapted to accept an LC connector extending from an exterior of the first side wall adjacent the second opening.

Respectfully submitted,

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Date:

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Date